

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
1	BRS	L7	56	(438/458).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 18:32			
2	BRS	L9	81	(438/459).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 18:34			
3	BRS	L15	78	("438"/\$).ccls. and (bond\$4 or join\$4) near oxide with (carrier or support\$4 or handle) near (wafer or substrate or die) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 18:36			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
4	BRS	L3	4	(438/464).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and align\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 18:43			
5	BRS	L16	16	("20030205796" "20030218236" "4962879" "5324687" "5532519" "5567653" "5712190" "6010591" "6025638" "6110806" "6279815" "6333553" "6365966" "6541871" "6633086" "6926937").PN. OR ("7005319").URPN.	US-PGPUB; USPAT; USOCR	2006/03/03 18:47			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
6	BRS	L4	9	(bond\$4 or join\$4) near oxide near (carrier or support\$4 or handle) near (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and align\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 18:51			
7	BRS	L5	23	(bond\$4 or join\$4) near oxide near (carrier or support\$4 or handle) near (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 18:52			
8	BRS	L6	7	(438/464).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 19:26			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com mm en ts	Er ro r De fi ni ti on	Er ro rs
9	BRS	L8	14	(438/456).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 19:02			
10	BRS	L17	46	("5006487" "5216490" "5310450" "5326726" "5329110").PN. OR ("5668033").URPN.	US-PGPUB; USPAT; USOCR	2006/03/03 19:07			
11	BRS	L10	2	(438/421).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 19:14			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
12	BRS	L13	21	((bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) near (wafer or substrate or die) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 19:15			
13	BRS	L11	28	(438/977).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 19:18			
14	BRS	L21	17	(bond\$4 or join\$4) near oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 19:29			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ro r De fi ni ti on	Er ro rs
15	BRS	L22	80	(bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 19:30			
16	BRS	L23	2	((bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 19:30			
17	BRS	L24	42	("438"/\$).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 19:34			

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18	BRS	L25	40	("257"/E21.\$).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 21:07			
19	BRS	L26	0	("257"/E21.606).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/03 21:08			